

PPP: FoF

Topic FP7-2012-NMP-ICT-FoF

Title: s- pactool

Objectives:

- Development of design tools based on newly available sensor data in microelectronic and micro-nano-system packaging chain

Expected results:

- Higher cost-efficiency/quality of assembly chain by supervision, monitoring and continuous tuning of process parameters
- Quality by design by embedded microsensors with multisensing features from the early phase of product development
- Design tools for the assembly of electronic boards for support of customization strategies
- Exploiting new materials, sandwich structures by involving the integration of micronanosensors technologies

PPP: FoF

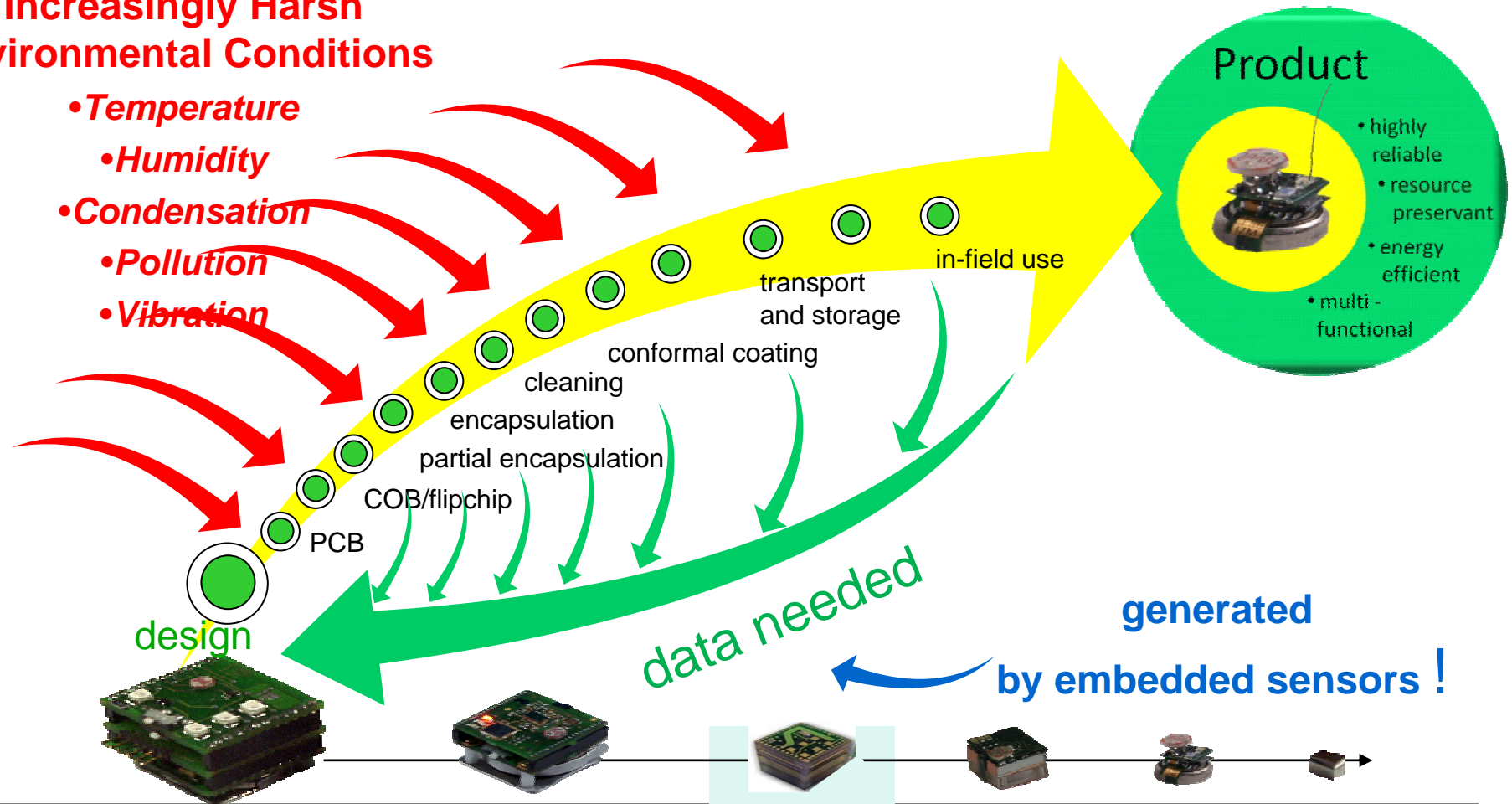
Topic FP7-2012-NMP-ICT-FoF

Title: s- pactool

Project/project structure:

Increasingly Harsh Environmental Conditions

- **Temperature**
- **Humidity**
- **Condensation**
- **Pollution**
- **Vibration**



Organisation:
CiS Forschungsinstitut für
Mikrosensorik und Photovoltaik GmbH

Contact person:
Arndt Steinke

E-mail:
asteinke@cismst.de

Phone:
+49 361 663 1420

PPP: FoF

Topic FP7-2012-NMP-ICT-FoF

Title: s- pactool

Known Partners				
S.No	Partner Name	Type	Country	Role in the Project
1	CiS Forschungsinstitut für Mikrosensorik und Photovoltaik GmbH	R&D	Germany	Embedded sensors
2	FhG IZM Berlin	R&D	Germany	Assembly technology
3	AMIC Angewandte Micromesstechnik GmbH	SME	Germany	Modelling
Required Partners				
S.No	Profile	Type	Country	Role in the project
	PCB, electronic assembly			
	Modelling&design			
	Assembly materials			

Organisation:
CiS Forschungsinstitut für
Mikrosensorik und Photovoltaik GmbH

Contact person:
Arndt Steinke

E-mail:
asteinke@cismst.de

Phone:
+49 361 663 1420